EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6595506").PN.	US-PGPUB; USPAT	OR	OFF	2006/06/27 07:58
L11	0	(118/715-733.ccls. 156/345.$.ccls.) and (quasam)	US-PGPUB; USPAT	OR	ON	2006/06/27 08:12
L12	0	(quasam) same suppport$3 same (substrate semiconductor wafer workpiece)	US-PGPUB; USPAT	OR	ON	2006/06/27 08:13
L13	4	(quasam)	US-PGPUB; USPAT	OR	ON	2006/06/27 08:21
L14	1	10/247,999	US-PGPUB; USPAT	OR	ON	2006/06/27 08:21
L15	2	10/247,499	US-PGPUB; USPAT	OR	ON	2006/06/27 08:21
L23	9	("5952060").URPN.	USPAT	OR	ON	2006/06/27 08:30
L24	37	("4340462" | "4491496" | "4534816" | "4612077" | "4948458" | "5006200" | "5022979" | "5200232" | "5262029" | "5268200" | "5308661" | "5366585" | "5393572" | "5494713" | "5522932" | "5569356" | "5641375" | "5680013" | "5798016" | "5812362" | "5820723" | "5824605" | "5838529" | "5846613" | "5863376" | "5879523" | "5885356" | "5888907" | "5891253" | "5895586" | "5904778" | "5916370" | "5952060" | "5989511" | "6015597" | "6048798" | "6071828").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/27 08:34
L25	1	24 and (dylyn dln)	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/27 08:34
L26	11	("6015597").URPN.	USPAT	OR	ON	2006/06/27 08:35
L27	75	(US-20030047283-$ or US-20050183669-$ or US-20050252454-$ or US-20060075969-$ or US-20050045106-$ or US-20040244695-$ or US-20040055709-$ or US-20030069632-$ or US-20040018749-$ or US-20030168168-$ or US-20050022746-$ or US-20030162314-$ or US-20050163985-$).did. or (US-6228471-$ or US-5352493-$ or US-6508911-$ or US-5508071-$ or US-6579833-$ or US-5695565-$ or US-5507874-$ or US-5638251-$ or US-H000566-$ or US-5786068-$ or US-5728465-$ or US-6998636-$ or US-6472062-$ or US-6200675-$ or US-7019399-$ or US-6669996-$ or US-6468642-$ or US-6696157-$ or US-5763851-$ or US-5466431-$ or US-5718976-$ or US-5795648-$ or US-4886565-$ or US-6753507-$ or US-6749729-$ or US-5711814-$).did. or (US-6595506-$ or US-6256187-$ or US-6135054-$ or US-5935323-$ or US-5812362-$ or US-5583736-$ or US-5166856-$ or US-5952060-$ or US-6537429-$ or US-6015597-$ or US-6551718-$ or US-5820723-$ or US-5846613-$ or US-5989511-$).did. or (WO-9712757-$ or WO-9640446-$ or WO-9639943-$ or WO-2005054539-$ or WO-9641034-$ or WO-9833948-$ or EP-856592-$ or WO-9740207-$).did. or (JP-01167211-$ or JP-2002246455-$ or JP-06348154-$ or JP-06025856-$).did. or (DE-1004004177-$ or WO-200159175-$ or WO-2005054539-$ or US-5466431-$ or WO-2005054540-$ or US-5352493-$ or JP-01167211-$ or US-5786068-$ or EP-856592-$ or JP-10096082-$).did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/06/27 08:44
L28	21	27 and titanium	US-PGPUB; USPAT	OR	ON	2006/06/27 09:01
L29	0	"2004055709"	US-PGPUB; USPAT	OR	ON	2006/06/27 09:01

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L30	1	"20040055709"	US-PGPUB; USPAT	OR	ON	2006/06/27 09:42
L31	26	parkhe-vijay.in. ahmann-kurt.in. tsai-matthew.in. sansoni-steve.in.	US-PGPUB; USPAT	OR	ON	2006/06/27 09:42
S7	6	(("6493629") or ("6340928") or ("6674403") or ("5977913") or ("6850735") or ("6714605")).PN.	US-PGPUB; USPAT	OR	OFF	2006/06/13 20:32
S8	3	(("5354381") or ("5572038") or ("5911832")).PN.	US-PGPUB; USPAT	OR	OFF	2006/03/23 16:23
S9	1	("6747464").PN.	US-PGPUB; USPAT	OR	OFF	2006/03/23 16:23
S10	0	(118/715-733.ccls. 156/345.$.ccls.) and (carbon same diamond same network same suppport$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:17
S11	0	((carbon with hydrogen with network) same suppport$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:35
S12	0	((carbon with hydrogen with network) same suppport$3 same (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:35
S13	0	((carbon with hydrogen) same suppport$3 same (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:34
S14	0	((carbon with hydrogen) same suppport$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/27 08:13
S15	801	((carbon with hydrogen) same support$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:34
S16	2	(118/715-733.ccls. 156/345.$.ccls.) and (carbon same diamond same network same support$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 20:43
S17	2	((carbon with hydrogen with network) same support$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:35
S18	2	((carbon with hydrogen with network) same support$3 same (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:35
S19	801	((carbon with hydrogen) same support$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:48
S20	39	(diamond same (carbon with hydrogen) same support$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:36
S21	2	S20 and nanocomposite	US-PGPUB; USPAT	OR	ON	2006/06/13 20:36
S22	8	S15 and nanocomposite	US-PGPUB; USPAT	OR	ON	2006/06/13 20:36
S23	36	(118/715-733.ccls. 156/345.$.ccls.) and (carbon same diamond same support$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 20:43
S24	3	((carbon with hydrogen) same support$3 same (substrate semiconductor wafer workpiece) same friction same hardness)	US-PGPUB; USPAT	OR	ON	2006/06/13 20:46
S25	1	((carbon with hydrogen) same support$3 same (substrate semiconductor wafer workpiece) same friction same hardness)	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:46
S26	1	((carbon with hydrogen) same support$3 same friction same hardness)	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:46
S27	2	((carbon with diamond) same support$3 same friction same hardness)	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:46
S28	44	((carbon same hydrogen same silicon same oxygen) same support$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:48
S29	1	((carbon same hydrogen same silicon same oxygen same composite) same support$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:48
S30	6	S28 and diamond	US-PGPUB; USPAT	OR	ON	2006/06/13 20:48
S31	0	("2003/0047283").URPN.	USPAT	OR	ON	2006/06/13 21:00

S32	636	bekaert	US-PGPUB; USPAT	OR	ON	2006/06/13 21:00
S33	40	bekaert and (diamond)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:00
S34	40	bekaert and (diamond diamond$1like)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:01
S35	2	("6200675").URPN.	USPAT	OR	ON	2006/06/13 21:03
S36	0	("6669996").URPN.	USPAT	OR	ON	2006/06/13 21:04
S37	0	("6669996").URPN.	USPAT	OR	ON	2006/06/13 21:04
S38	2	("6200675").URPN.	USPAT	OR	ON	2006/06/13 21:04
S39	0	(118/715-733.ccls. 156/345.$.ccls.) and (cdylyn)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:08
S40	0	(118/715-733.ccls. 156/345.$.ccls.) and (dylyn)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:08
S41	31	(dylyn)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:08
S42	0	(118/715-733.ccls. 156/345.$.ccls.) and (S41)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:08
S43	7	(S41) and (support$3 with (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 21:09
S44	0	(delryn) and (support$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:09
S45	0	(dylyn) and (support$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:10
S46	0	(dln) and (support$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:11
S47	0	(belaert) and (support$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:11
S48	2	(bekaert) and (support$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:11
S49	420	(118/715-733.ccls. 156/345.$.ccls.) and (carbon same (diamond diamond$1like) suppport$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:17
S50	9617	(118/715-733.ccls. 156/345.$.ccls.) and (carbon same (diamond diamond$1like) support$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:17
S51	36	(118/715-733.ccls. 156/345.$.ccls.) and (carbon same (diamond diamond$1like)same support$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:18
S52	1034	(shield$3 lin$3) with (provid$3 cover$3 protect$3) with (bottom) with chamber	US-PGPUB; USPAT	OR	ON	2006/06/14 09:21
S53	70	(118/715-733.ccls. 156/345.$.ccls.) and ((shield$3 lin$3) with (provid$3 cover$3 protect$3) with (bottom) with chamber)	US-PGPUB; USPAT	OR	ON	2006/06/14 09:21
S54	55	(118/715-733.ccls. 156/345.$.ccls.) and ((shield shielding liner) with (provid$3 cover$3 protect$3) with (bottom) with chamber)	US-PGPUB; USPAT	OR	ON	2006/06/14 09:31
S55	9	(118/715-733.ccls. 156/345.$.ccls.) and ((inner$1chamber sub$1chamber) with (liner shield))	US-PGPUB; USPAT	OR	ON	2006/06/14 09:32
S56	2	(("5352493") or ("5466431")).PN.	US-PGPUB; USPAT	OR	OFF	2006/06/15 17:46
S57	44	("5466431").URPN.	USPAT	OR	ON	2006/06/15 17:48
S58	9	S57 and susceptor	US-PGPUB; USPAT	OR	ON	2006/06/15 17:49
S59	0	dln with susceptor	US-PGPUB; USPAT	OR	ON	2006/06/15 17:49
S60	0	dln with susceptor	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:49

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S61	3	dln and (118/728-732.ccls. 156/345.51-345.54.ccls.)	US-PGPUB; USPAT	OR	ON	2006/06/15 17:51
S62	961	dln	US-PGPUB; USPAT	OR	ON	2006/06/15 17:50
S63	3	dln and (118/728-732.ccls. 156/345.51-345.55.ccls.)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:01
S64	178	dln and ((substrate wafer semiconductor substrate) same (support$4 hold$4 table susceptor))	US-PGPUB; USPAT	OR	ON	2006/06/15 17:53
S65	123	dln and ((substrate wafer semiconductor substrate) with (support$4 hold$4 table susceptor))	US-PGPUB; USPAT	OR	ON	2006/06/15 17:52
S66	9	dln same((substrate wafer semiconductor substrate) with (support$4 hold$4 table susceptor))	US-PGPUB; USPAT	OR	ON	2006/06/15 17:52
S67	0	dln and ((substrate wafer semiconductor substrate) same (support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:20
S68	0	dln and ((substrate wafer semiconductor substrate) and (support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:54
S69	2	dln and ((support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:54
S70	7	diamond and nanocomposite and ((support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:56
S71	17	diamond and nanocomposite and (substrate wafer)	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:56
S72	5	(diamond$5 with carbon with $5composite) and (118/728-732. ccls. 156/345.51-345.55.ccls.)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:00
S73	6	(diamond$5 with carbon with $5composite) and (susceptor)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:00
S74	83	(diamond same carbon) and (118/728-732.ccls. 156/345.51-345.55.ccls.)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:24
S75	70	(diamond with carbon) and (118/728-732.ccls. 156/345.51-345.55.ccls.)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:14
S76	7	"269"/$.ccls. and (diamond with carbon)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:15
S77	5	("6595506").URPN.	USPAT	OR	ON	2006/06/15 18:16
S78	0	("6595506").URPN. and diamond	USPAT	OR	ON	2006/06/15 18:16
S79	0	("6595506").URPN. and diamond$5	USPAT	OR	ON	2006/06/15 18:16
S80	0	S77 and diamond$5	USPAT	OR	ON	2006/06/15 18:16
S81	12	("5166856" | "5324012" | "5583736" | "5707409" | "5812362" | "5924917" | "5935323" | "5989693" | "6086796" | "6135054" | "6256187" | "6316734").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/15 18:17
S82	2	"01167211"	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:20
S83	305	(diamond$5 with carbon) and ((substrate wafer semiconductor substrate) same (support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:24
S84	283	(diamond$5 with carbon) and ((substrate wafer semiconductor substrate) with (support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:25
S85	170	(diamond$5 with carbon) same ((substrate wafer semiconductor substrate) with (support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:25
S86	68	("diamond-like" with carbon) same ((substrate wafer semiconductor substrate) with (support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:25
S87	72	(diamond$1like with carbon) same ((substrate wafer semiconductor substrate) with (support$4 hold$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:37

S88	35	(diamond$1like with carbon) same ((substrate wafer semiconductor substrate) with (support$4 hold$4 table susceptor chuck electrostatic "esc" clamp)) same (protect$4 prohibit$4 wear resist$4 hard$4 friction$4 elas$7 abras$5)	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:28
S89	1	("5952060").PN.	US-PGPUB; USPAT	OR	OFF	2006/06/15 18:34
S90	1	(diamond$1like with carbon with nano$1composite) and electrostatic	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:38
S91	6	(diamond$1like with carbon with nano$1composite) and electrostatic	US-PGPUB; USPAT	OR	ON	2006/06/15 18:39
S92	9	(diamond$1like with nano$1composite) and electrostatic	US-PGPUB; USPAT	OR	ON	2006/06/15 18:41
S93	10	(diamond$1like with nano$1composite) and electrostatic$5	US-PGPUB; USPAT	OR	ON	2006/06/15 18:41
S94	1	S93 not S92	US-PGPUB; USPAT	OR	ON	2006/06/15 18:41
S95	1	(diamond$1like with nano$1composite) and electrostatic$5	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:42
S96	5	"856592"	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:42
S97	2	(("5352493") or ("6228471")).PN.	US-PGPUB; USPAT	OR	OFF	2006/06/26 17:00
S98	1	("20030047283").PN.	US-PGPUB; USPAT	OR	OFF	2006/06/26 17:00